

# SLOVENSKI STANDARD

## SIST EN IEC 62680-1-2:2023

01-marec-2023

Nadomešča:

SIST EN IEC 62680-1-2:2021

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**Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2. del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB (IEC 62680-1-2:2022)**

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2022)

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-2: Gemeinsame Komponenten - Festlegung für die USB-Stromversorgung (IEC 62680-1-2:2022)

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Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie 1-2: Composants communs - Spécification de l'alimentation électrique par port USB (IEC 62680-1-2:2022)

**Ta slovenski standard je istoveten z: EN IEC 62680-1-2:2022**

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**ICS:**

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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**SIST EN IEC 62680-1-2:2023**

**en,fr,de**



EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN IEC 62680-1-2**

October 2022

ICS 29.220; 33.120; 35.200

Supersedes EN IEC 62680-1-2:2021

English Version

**Universal serial bus interfaces for data and power - Part 1-2:  
Common components - USB Power Delivery specification  
(IEC 62680-1-2:2022)**

Interfaces de bus universel en série pour les données et  
l'alimentation électrique - Partie 1-2: Composants communs  
- Spécification de l'alimentation électrique par port USB  
(IEC 62680-1-2:2022)

Schnittstellen des Universellen Seriellen Busses für Daten  
und Energie - Teil 1-2: Gemeinsame Komponenten -  
Festlegung für die USB-Stromversorgung  
(IEC 62680-1-2:2022)

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The text of document 100/3716/CDV, future edition 6 of IEC 62680-1-2, prepared by IEC/TC 100 "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-2:2022.

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# NORME INTERNATIONALE



**Universal serial bus interfaces for data and power –  
Part 1-2: Common components – USB Power Delivery specification**

**Interfaces de bus universel en série pour les données et l'alimentation  
électrique –  
Partie 1-2: Composants communs – Spécification de l'alimentation électrique  
par port USB**

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**UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –****Part 1-2: Common components – USB Power Delivery specification**

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

Draft	Report on voting
100/3716/CDV	100/3763/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication Universal Serial Bus Power Delivery Specification Revision 3.1, Version 1.1.

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**Universal Serial Bus  
Power Delivery Specification**

**Revision:**

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**Version:**

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Josh Averyt	Microchip Technology Inc.	Krishnan TN	NXP Semiconductors
Kiet Tran	Microchip Technology Inc.	Michael Joehren	NXP Semiconductors
Mark Bohm	Microchip Technology Inc.	Robert de Nie	NXP Semiconductors
Matthew Kalibat	Microchip Technology Inc.	Rod Whitby	NXP Semiconductors
Mick Davis	Microchip Technology Inc.	Vijendra Kuroodi	NXP Semiconductors
Prasanna	Microchip Technology Inc.	Winston Langeslag	NXP Semiconductors
Vengateshan		Robert Heaton	Obsidian Technology
Rich Wahler	Microchip Technology Inc.	Andrew Yoo	ON Semiconductor
Richard Petrie	Microchip Technology Inc.	Brady Maasen	ON Semiconductor
Ronald Kunin	Microchip Technology Inc.	Bryan McCoy	ON Semiconductor
Shannon Cash	Microchip Technology Inc.	Christian Klein	ON Semiconductor
Thomas Farkas	Microchip Technology Inc.	Cor Voorwinden	ON Semiconductor
Venkataraman	Microchip Technology Inc.	Edward Berrios	ON Semiconductor
Krishnamoorthy		Michael Smith	ON Semiconductor
Andrew Yang	Microsoft Corporation	Oscar Freitas	ON Semiconductor
Anthony Chen	Microsoft Corporation	Tom Duffy	ON Semiconductor
Arvind Murching	Microsoft Corporation	Brian Collins	Parade Technologies Inc.
Dave Perchlik	Microsoft Corporation	Craig Wiley	Parade Technologies Inc.
David Voth	Microsoft Corporation	Aditya Kulkarni	Power Integrations
Geoff Shew	Microsoft Corporation	Akshay Nayaknur	Power Integrations
Jayson Kastens	Microsoft Corporation	Amruta Patra	Power Integrations
Kai Inha	Microsoft Corporation	Rahul Joshi	Power Integrations
Marwan Kadado	Microsoft Corporation	Ricardo Pregiteer	Power Integrations
Michelle Bergeron	Microsoft Corporation	Shruti Anand	Power Integrations
Nathan Sherman	Microsoft Corporation	Amit gupta	Qualcomm, Inc.
Rahul Ramadas	Microsoft Corporation	George Paparrizos	Qualcomm, Inc.
Randy Aull	Microsoft Corporation	Giovanni Garcea	Qualcomm, Inc.
Shiu Ng	Microsoft Corporation	Jack Pham	Qualcomm, Inc.
Tieyong Yin	Microsoft Corporation	James Goel	Qualcomm, Inc.
Timo Toivola	Microsoft Corporation	Joshua Warner	Qualcomm, Inc.
Toby Nixon	Microsoft Corporation	Karyn Vuong	Qualcomm, Inc.
Vahid Vassey	Microsoft Corporation	Lalan Mishra	Qualcomm, Inc.
Vivek Gupta	Microsoft Corporation	Vamsi Samavedam	Qualcomm, Inc.
Yang You	Microsoft Corporation	Vatsal Patel	Qualcomm, Inc.
Adib Al Abaji	Molex LLC	Chris Sporck	Qualcomm, Inc.
Aaron Xu	Monolithic Power Systems Inc.	Craig Aiken	Qualcomm, Inc.
Bo Zhou	Monolithic Power Systems Inc.	Narendra Mehta	Qualcomm, Inc.
Christian Sporck	Monolithic Power Systems Inc.	Terry Remple	Qualcomm, Inc.
Di Han	Monolithic Power Systems Inc.	Will Kun	Qualcomm, Inc.
Zhihong Yu	Monolithic Power Systems Inc.	Yoram Rimoni	Qualcomm, Inc.
Dan Wagner	Motorola Mobility Inc.	Fan-Hau Hsu	Realtek Semiconductor Corp.
Ben Crowe	MQP Electronics Ltd.	Tsung-Peng Chuang	Realtek Semiconductor Corp.
Pat Crowe	MQP Electronics Ltd.	Atsushi Mitamura	Renesas Electronics Corp.
Sten Carlsen	MQP Electronics Ltd.	Bob Dunstan	Renesas Electronics Corp.
Kenji Oguma	NEC Corporation	Brian Allen	Renesas Electronics Corp.
Frank Borngräber	Nokia Corporation	Dan Aoki	Renesas Electronics Corp.
Kai Inha	Nokia Corporation	Hajime Nozaki	Renesas Electronics Corp.
Pekka Leinonen	Nokia Corporation	John Carpenter	Renesas Electronics Corp.
Richard Petrie	Nokia Corporation	Kiichi Muto	Renesas Electronics Corp.
Sten Carlsen	Nokia Corporation	Masami Katagiri	Renesas Electronics Corp.
Abhijeet Kulkarni	NXP Semiconductors	Nobuo Furuya	Renesas Electronics Corp.
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